



# SOT984-1

DFN2514U-12: plastic thermal enhanced extremely thin small outline package; no leads; 12 terminals

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	D (double)
<b>Package type descriptive code</b>	DFN2514U-12
<b>Package type industry code</b>	DFN2514U-12
<b>Package style descriptive code</b>	HXSON (thermal enhanced extremely thin small outline; no leads)
<b>Package style suffix code</b>	U (UTLP based)
<b>Package body material type</b>	P (plastic)
<b>IEC package outline code</b>	- - -
<b>JEITA package outline code</b>	- - -
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	14-11-2007

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	2.45	-	2.5	2.55	mm
E	package width	1.3	-	1.35	1.4	mm
A	seated height	[tbd]	-	[tbd]	0.5	mm
e	nominal pitch	-	-	0.4	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	12	-	

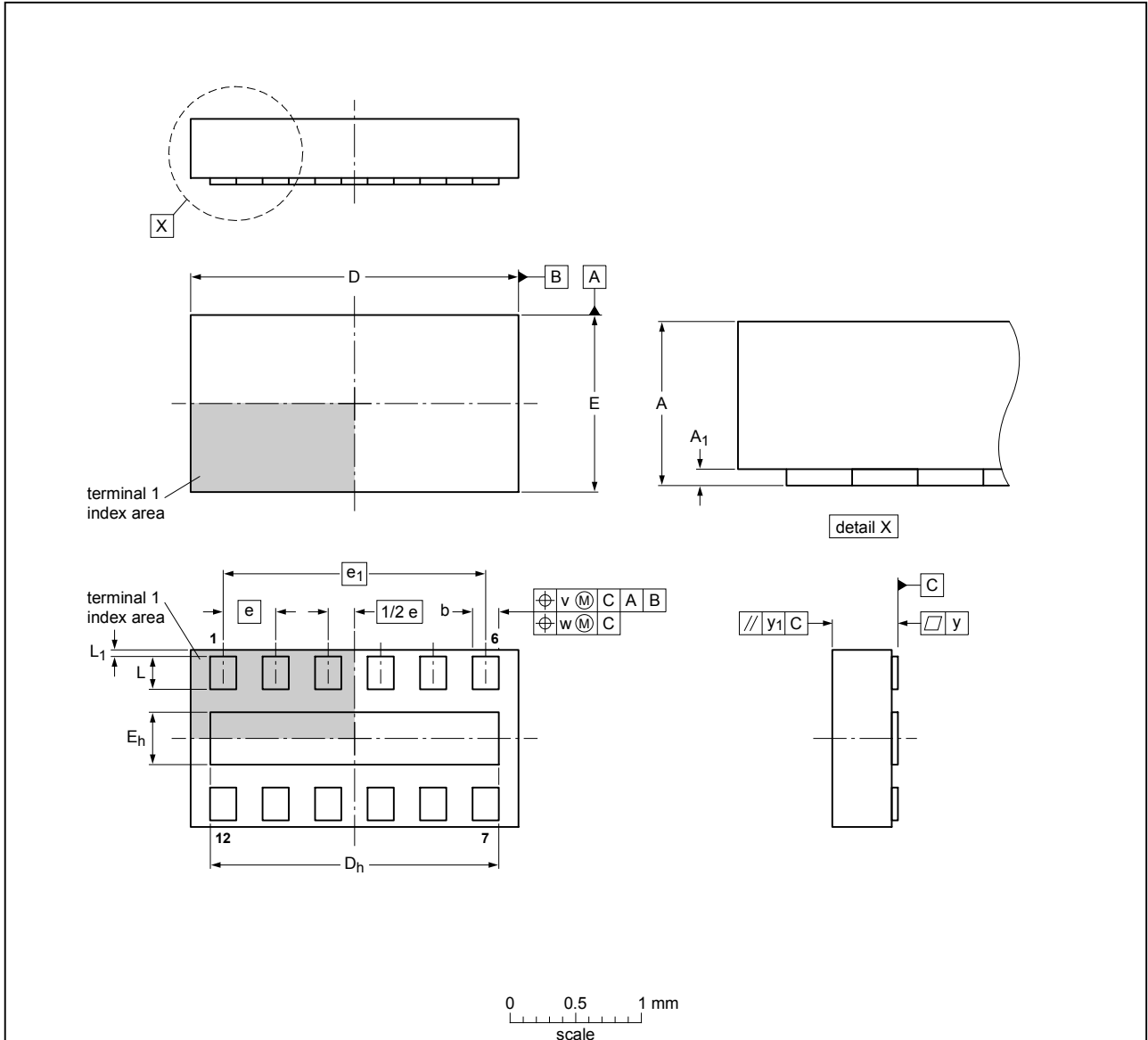


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## 2. Package outline

HXSON12U: plastic thermal enhanced extremely thin small outline package; no leads; 12 terminals; UTLP based; body 1.35 x 2.5 x 0.5 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A <sub>max</sub>	A <sub>1</sub>	b	D	D <sub>n</sub>	E	E <sub>n</sub>	e	e <sub>1</sub>	L	L <sub>1</sub>	v	w	y	y <sub>1</sub>
mm	0.5	0.05 0.00	0.25 0.15	2.55 2.45	2.3 2.1	1.4 1.3	0.5 0.3	0.4	2	0.35 0.15	0.09 0.00	0.1	0.05	0.05	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT984-1	---		---			07-01-12 07-11-14

Fig. 1. Package outline DFN2514U-12 (SOT984-1)

### 3. Soldering

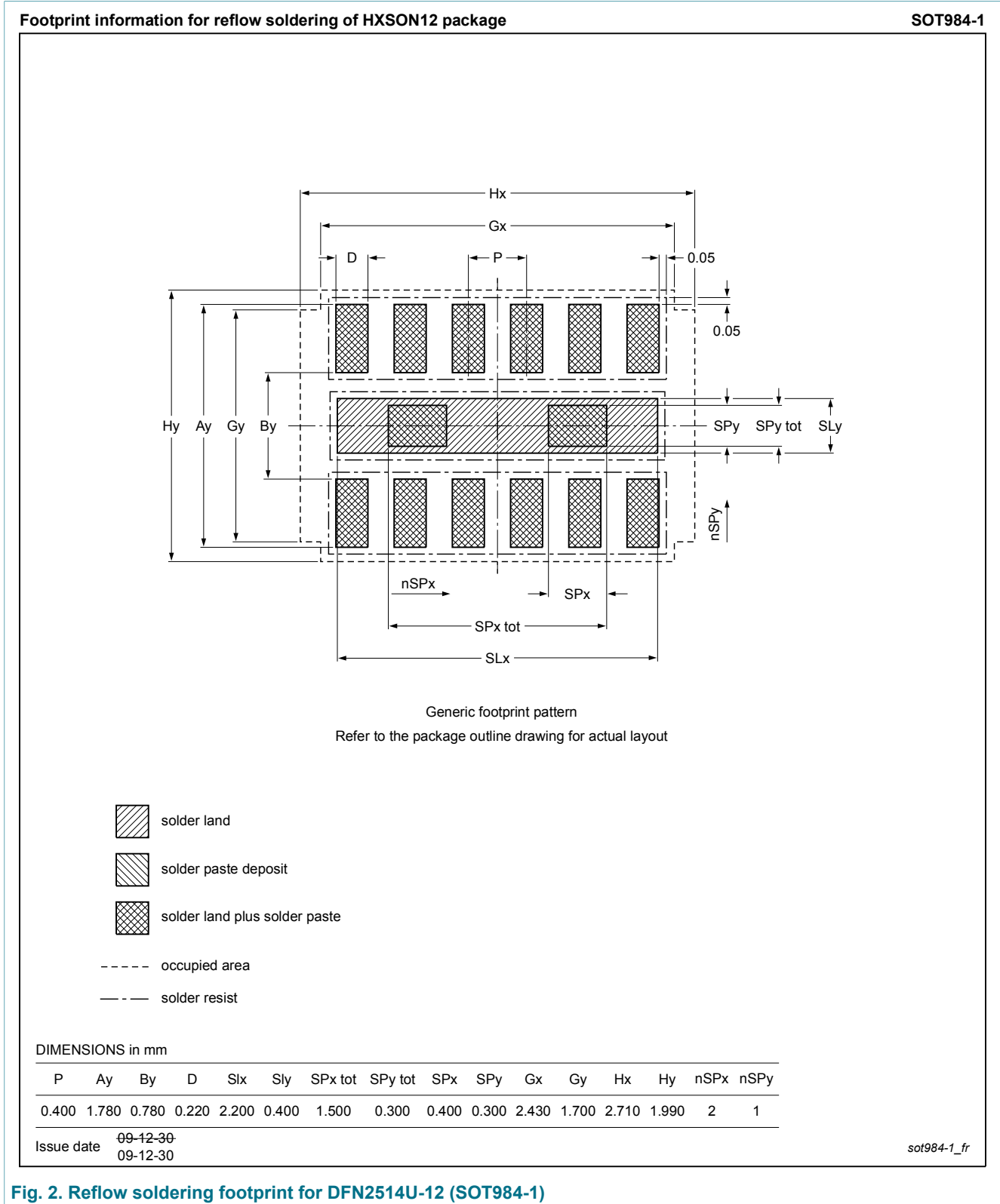


Fig. 2. Reflow soldering footprint for DFN2514U-12 (SOT984-1)

## 4. Legal information

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